

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSS84P H6327	**Issued**	29. August 2013
MA#	MA001097556		
Package	PG-SOT23-3-5	**Weight***	9.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.007	0.07		717	
	non noble metal	tin	7440-31-5	0.002	0.02		185	
	inorganic material	silicon	7440-21-3	0.076	0.81	0.90	8125	9027
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		970	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		323	
	non noble metal	copper	7440-50-8	3.000	32.19	32.33	321912	323270
wire	non noble metal	copper	7440-50-8	0.008	0.09	0.09	889	889
encapsulation	organic material	carbon black	1333-86-4	0.058	0.62		6202	
	plastics	epoxy resin	-	1.243	13.34		133353	
	inorganic material	silicondioxide	60676-86-0	4.480	48.06	62.02	480689	620244
leadfinish	non noble metal	tin	7440-31-5	0.150	1.61	1.61	16055	16055
plating	noble metal	silver	7440-22-4	0.284	3.05	3.05	30515	30515
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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